

TEMIC

Siliconix

VQ1001J/P

N-Channel Enhancement-Mode MOS Transistors

Product Summary

Part Number	$V_{(BR)DSS}$ Min (V)	$r_{DS(on)}$ Max (Ω)	$V_{GS(th)}$ (V)	I_D (A)
VQ1001J	30	1 @ $V_{GS} = 12$ V	0.8 to 2.5	0.83
VQ1001P		1 @ $V_{GS} = 12$ V	0.8 to 2.5	0.53

Features

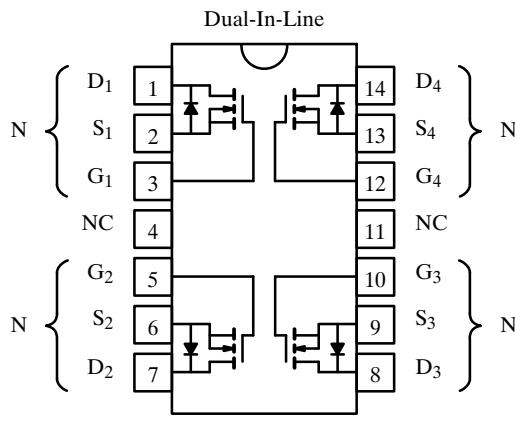
- Low On-Resistance: 0.85 Ω
- Low Threshold: 1.4 V
- Low Input Capacitance: 38 pF
- Fast Switching Speed: 9 ns
- Low Input and Output Leakage

Benefits

- Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

Applications

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays



Plastic: VQ1001J
Sidebrazed: VQ1001P

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Single	Total Quad	Unit
Drain-Source Voltage	V_{DS}	30		V
Gate-Source Voltage		± 30		
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	0.83		A
		0.53		
Pulsed Drain Current	I_{DM}	3		
Power Dissipation (Single)	P_D	1.3	2	W
		0.52	0.8	
Maximum Junction-to-Ambient (Single)	R_{thJA}	96	62.5	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J, T_{stg}	−55 to 150		$^\circ\text{C}$

Notes

a. Pulse width limited by maximum junction temperature.

Specifications^a

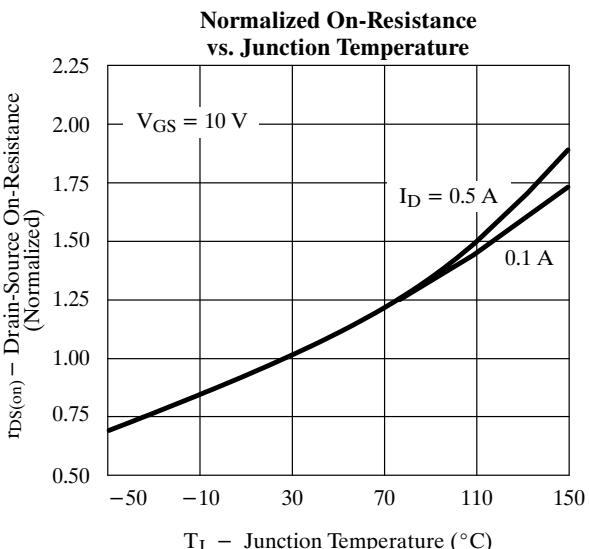
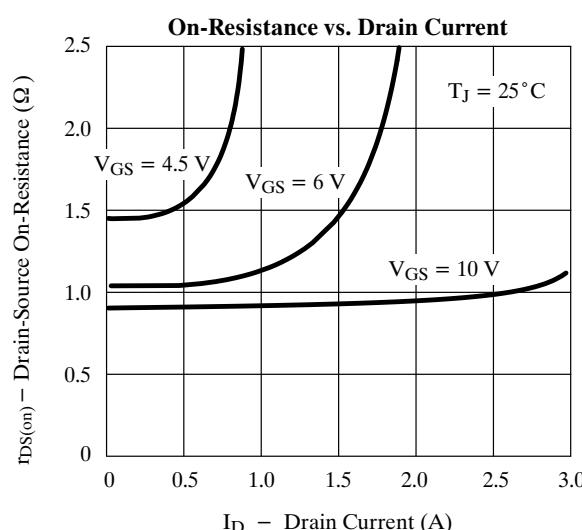
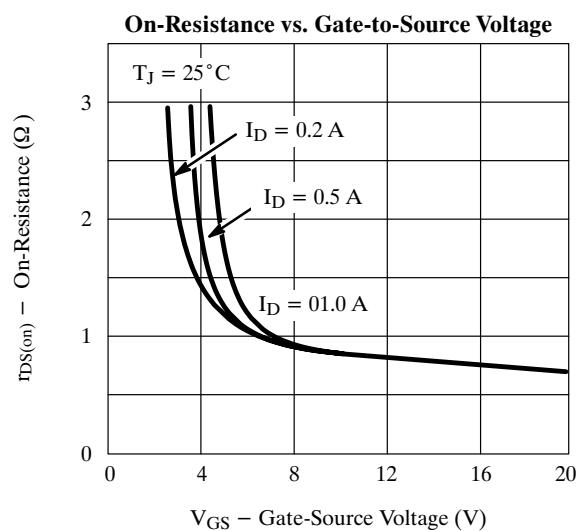
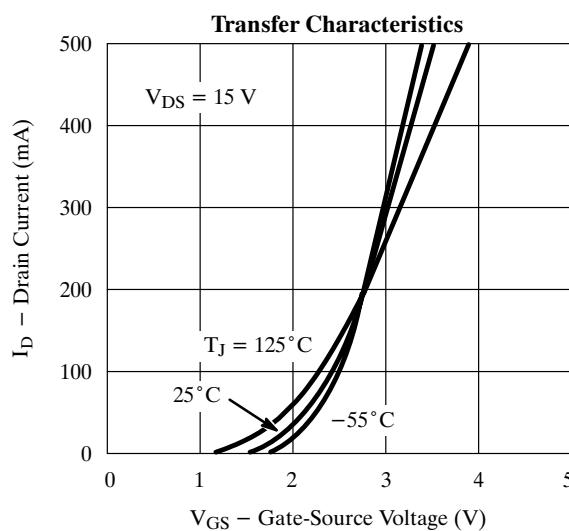
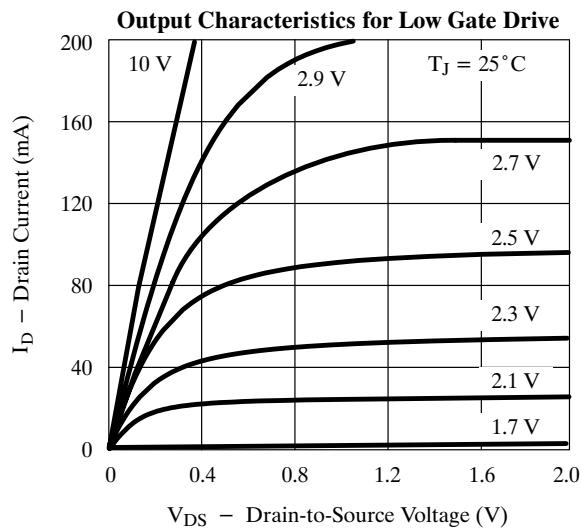
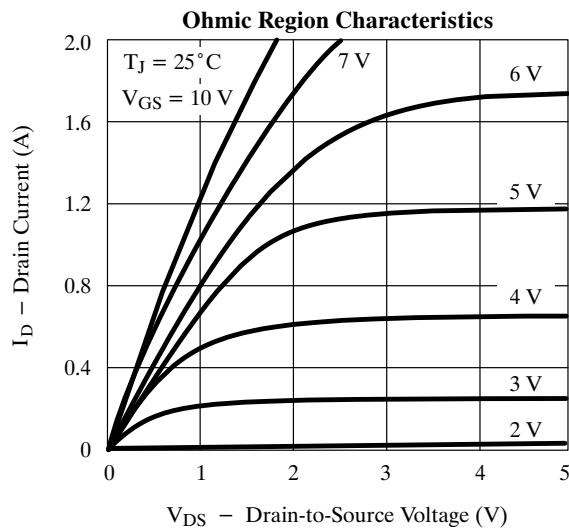
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ ^b	Max	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 10 µA	30	45		V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 1 mA	0.8	1.5	2.5	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 15 V T _J = 125°C			± 100	nA
					± 500	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			10	µA
		V _{DS} = 24 V, V _{GS} = 0 V, T _J = 125°C			500	
On-State Drain Current ^c	I _{D(on)}	V _{DS} = 10 V, V _{GS} = 12 V	2	3.5		A
Drain-Source On-Resistance ^c	r _{D(on)}	V _{GS} = 5 V, I _D = 0.2 A		1.2	1.75	Ω
		V _{GS} = 12 V, I _D = 1 A T _J = 125°C		0.8	1	
Forward Transconductance ^c	g _{fs}	V _{DS} = 10 V, I _D = 0.5 A	200	500		mS
Dynamic						
Input Capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		38	110	pF
Output Capacitance	C _{oss}			33	110	
Reverse Transfer Capacitance	C _{rss}			8	35	
Switching^d						
Turn-On Time	t _{ON}	V _{DD} = 15 V, R _L = 23 Ω, I _D ≈ 0.6 A V _{GEN} = 10 V, R _G = 25 Ω		9	30	ns
Turn-Off Time	t _{OFF}			14	30	

Notes

- a. T_A = 25°C unless otherwise noted.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Pulse test: PW ≤ 300 µs duty cycle ≤ 2%.
- d. Switching time is essentially independent of operating temperature.

VNDQ03

Typical Characteristics (25°C Unless Otherwise Noted)



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